Radiation-Hardened Electronics Market by Component (Power Management, ASIC, Logic, Memory & FPGA), Manufacturing Technique (RHBD & RHPB), Application, and Geography - Global Forecast to 2022

Description: Advancements in FPGA & multicore processor technologies for defense and space applications is one of the major factors fueling the growth of this market. In addition, the demand from the communication satellite segment for rad-hard electronics is also expected to drive the growth of the radiation-hardened electronics market. The key restraining factor for the growth of the radiation-hardened electronics market is the high cost of development and design associated with the development of rad-hard components.

“The radiation-hardened electronics market for space applications is expected to grow at a high rate during the forecast period.”

Factors such as, increased demand from commercial and military satellite industry for radiation-hardened electronic components, has led to the growth of rad-hard market in these applications. On the other hand, the increased bandwidth requirements and the need for pointing of telecommunication satellites, and the demand for rad-hard components such as multiplexers, diodes, and detectors is also growing in these applications.

“North Americas and APAC are the major markets for radiation-hardened electronics.”

North America is expected to hold the largest share of the radiation-hardened electronics market during the forecast period, while the market in APAC is expected to grow at the highest rate during the same period. China, Japan, and India are some of the major countries driving the growth of the radiation-hardened electronics market in APAC. A significant number of prominent companies offering radiation-hardened electronic components are based out of North America and APAC. This is one of the major factors driving the growth of the radiation-hardened electronics market in North America and APAC.

In the process of determining and verifying the market size for several segments and subsegments gathered through secondary research, extensive primary interviews have been conducted with key people in the radiation-hardened electronics industry.

The break-up of primary participants for the report has been shown below:
- By Company Type: Tier 1 – 35 %, Tier 2 – 45%, and Tier 3 – 20%
- By Designation: C-Level– 35%, Director Level – 25%, and Others – 40%
- By Region: North America – 45%, Europe – 20%, APAC – 30%, and RoW – 5%

The report also profiles the key players in the radiation-hardened electronics market and analyzes their market ranking. The prominent players profiled in this report are BAE Systems (U.K.), Honeywell Aerospace (U.S.), Microsemi Corporation (U.S.), Atmel Corporation (U.S.) Xilinx, Inc. (U.S.), Intersil Corporation (U.S.), Texas Instruments, Inc. (U.S.), STMicroelectronics NV (Switzerland), Maxwell Technologies, Inc. (U.S.), and Linear Technology Corporation (U.S.), among others.

Research Coverage:
This research report categorizes the global radiation-hardened electronics market on the basis of component, manufacturing technique, application, and geography. The report also provides the Porter's five forces analysis, along with a description of each of its forces and their respective impact on the radiation-hardened electronics market; description of major drivers, restraints, challenges, and opportunities pertaining to the market; value chain analysis; and market ranking analysis.

Reasons to buy the Report
The report would help leaders/new entrants in this market in the following ways:
1. This report segments the radiation-hardened electronics market comprehensively and provides the closest market size estimation for all subsegments across different regions.
2. The report helps stakeholders understand the pulse of the market and provides them with the
information on key drivers, restraints, challenges, and opportunities for market growth.

3. This report would help stakeholders understand their competitors better and gain more insights to improve their position in the business. The competitive landscape section includes competitor ecosystem, new product developments, partnerships, and mergers & acquisitions.

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